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## **BGA packaging of APV-25 Chip**

*Tuesday 2 October 2012 11:30 (15 minutes)*

We have developed an easy to prototype BGA package for the APV-25S charge sensitive pre-amp ASIC. The APV chip, developed for the CMS tracker, is often used to readout GEM as well as silicon strip detectors. To reduce prototyping and development costs we have packaged the APV chips into a BGA. This allows front-end electronics to be developed and tested without the need to design boards with the very fine pitch wire bonding. It also allows boards with failed chips to be repaired easily. We will discuss the design, and production experience, and recommendations for future users.

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